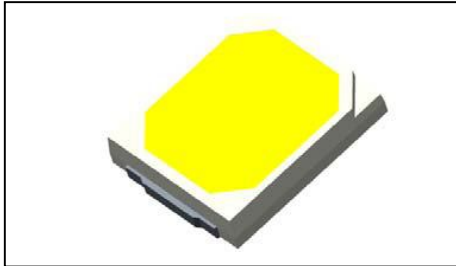


REFOND P/N
RF-W HV32DS-FF-E3

REFOND
Mass Product

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4.1 Handling Precautions	



The White LED which was fabricated using a blue chip and the phosphor

LED

2.8mmX3.5mmX0.7mm

PLCC-2 Package.

Extremely wide viewing angle.

Suitable for all SMT assembly and solder process.

SMT

Available on tape and reel.

Moisture sensitivity level: Level 3. Level 3

RoHS compliant. RoHS

Indoor lighting.

Bulb lighting.

General indoor applications.

Table 1-3

VG1	VG2
52.4-53.2	53.2-5
FC4	
120-130	
FC5	
130	

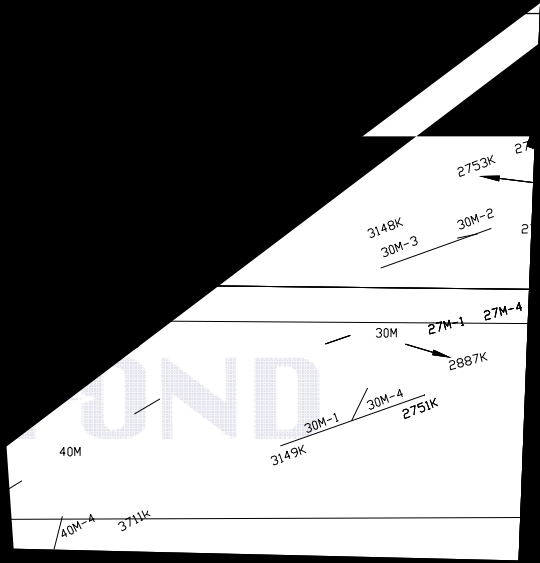


Table 1-4

27M-1

27M-2



Table 1-5

CCT	CIE Kit	Reel 1	Reel 2
2700K	Kit 1	27M	27M
	Kit 2	27M-1	27M-2
	Kit 3	27M-3	27M-4
3000K	Kit 1	30M	30M
	Kit 2	30M-1	30M-2
	Kit 3	30M-3	30M-4
4000K	Kit 1	40M	40M
	Kit 2	40M-1	40M-2
	Kit 3	40M-3	40M-4
5000K	Kit 1	50M	50M
	Kit 2	50M-1	50M-2
	Kit 3	50M-3	50M-4
5700K	Kit 1	57M	57M
	Kit 2	57M-1	57M-2
	Kit 3	57M-3	57M-4
6500K	Kit 1	65M	65M
	Kit 2	65M-1	65M-2
	Kit 3	65M-3	65M-4



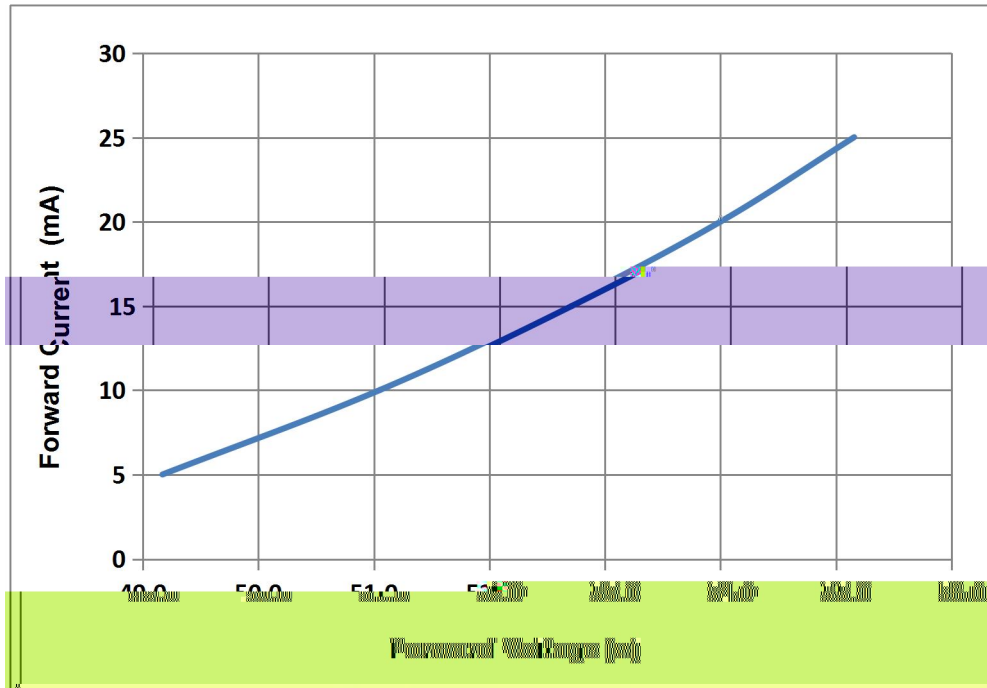


Fig 1-7 Forward Voltage Vs. Forward Current

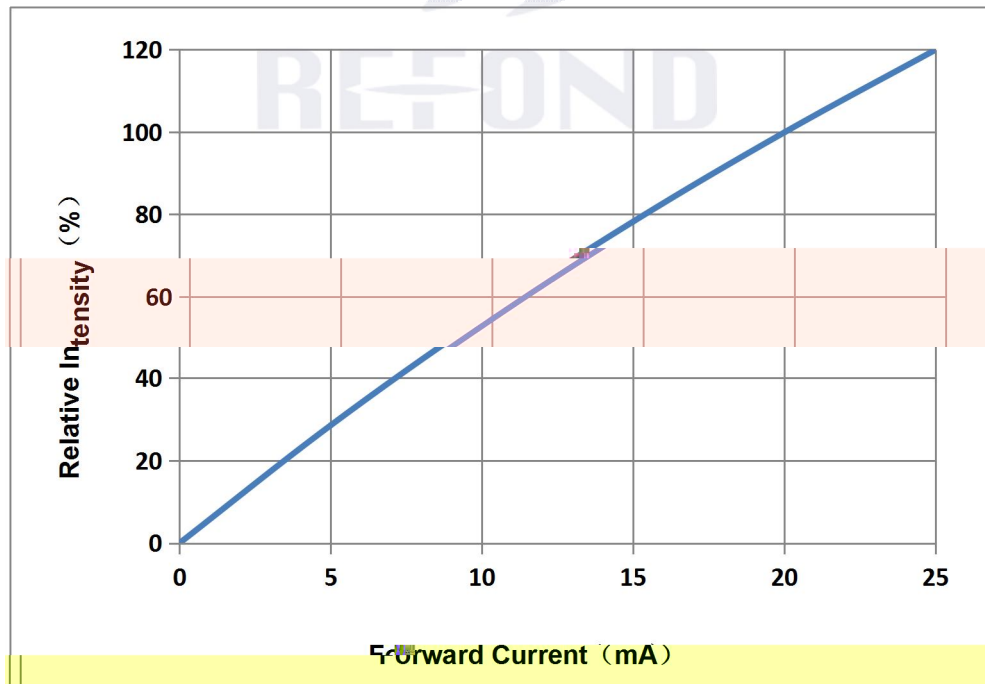


Fig 1-8 Forward Current Vs. Relative Intensity



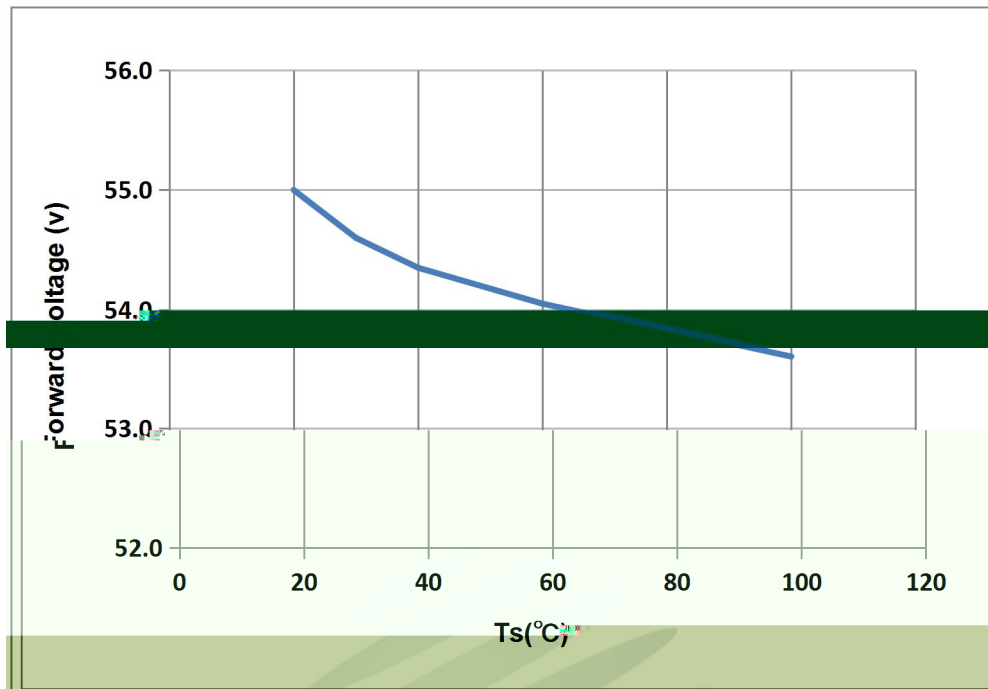


Fig 1-11 Forward Voltage Vs Solder Temperature

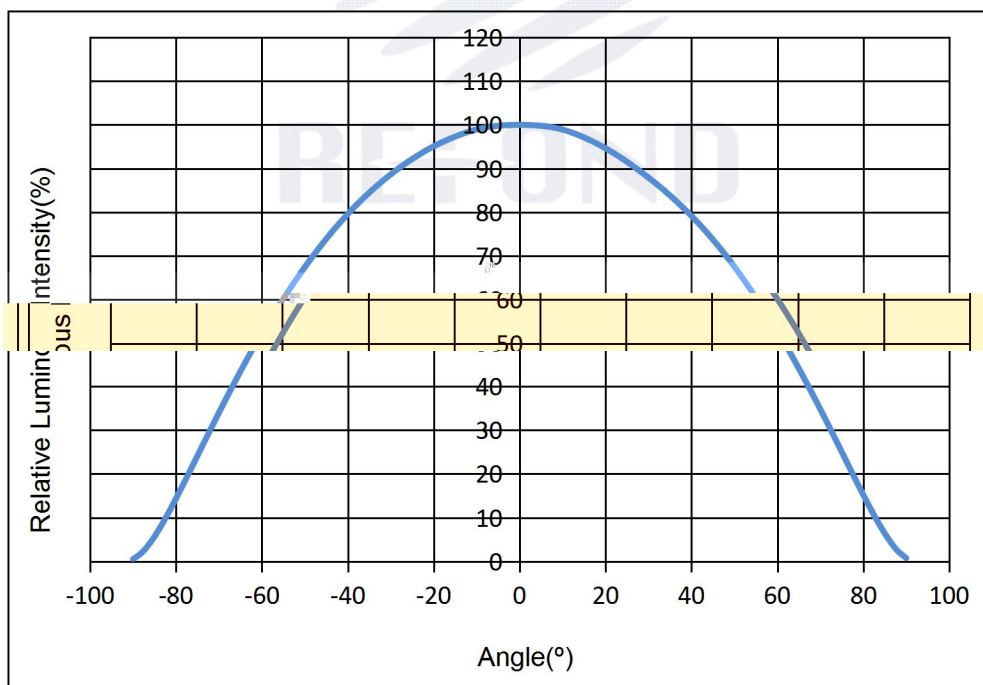


Fig 1-12 Radiation diagram

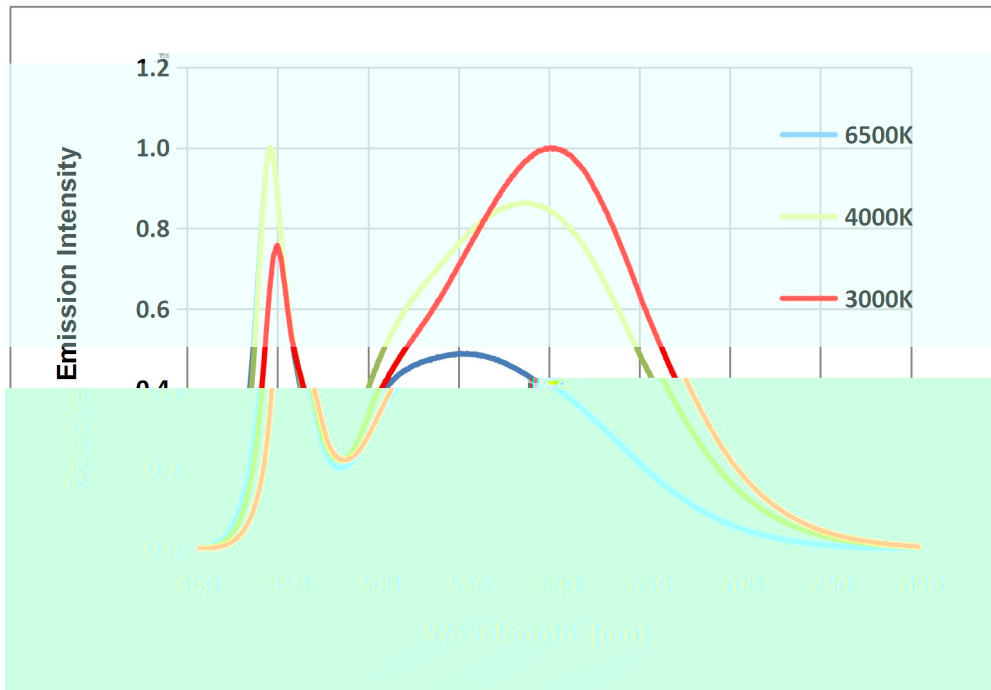


Fig 1-13 Spectrum Distribution

REFOND

Specification



Fig 2-3 Title

PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code
	Luminous flux
XY	Chromaticity Bin
V _F	Forward Voltage
WLD	Wavelength
QTY	Packing Quantity
DATE	Made Date

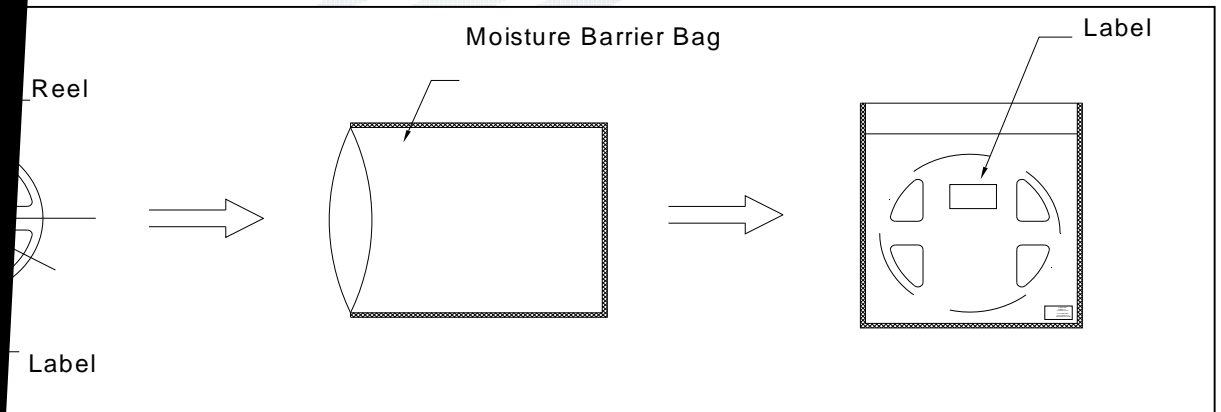


Fig.2-4Title

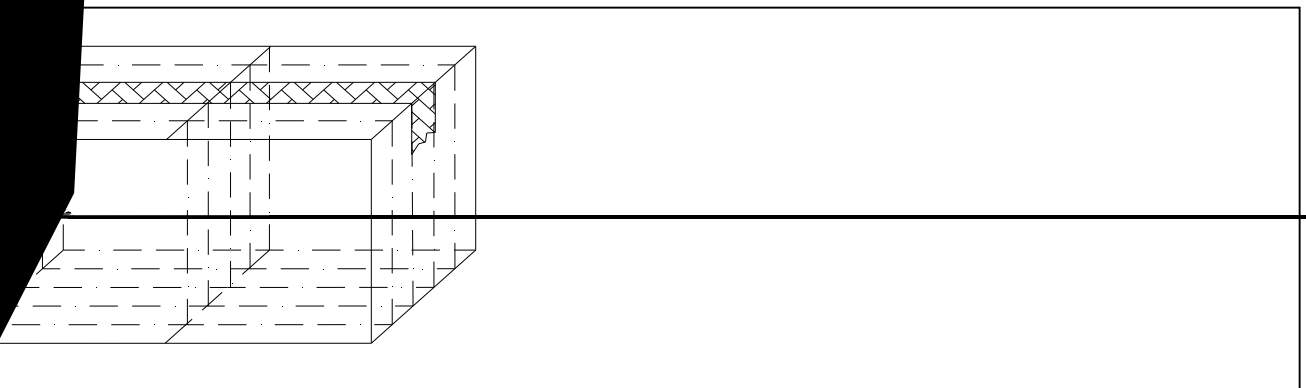


Fig.2-5Title

Notes

(1) Reflow soldering should not be done more than two times. In the case of more than 24 hours passed soldering after first, LEDs will be damaged.

(2) When soldering, do not put stress on the LEDs during heating.

3.1.1 Soldering Iron

(1) When hand soldering, keep the temperature of iron below less 300 less than 3 seconds

(2) The hand solder should be done only one time.

3.1.2 Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or will not be damaged by repairing.

LED

3.1.3 Cautions

(1) The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be influence to the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozzle, the pressure on the silicone resin should be proper. LED

(2) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board. LED

(4) Handle the component along the side surface by using forceps or appropriate tools; do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.

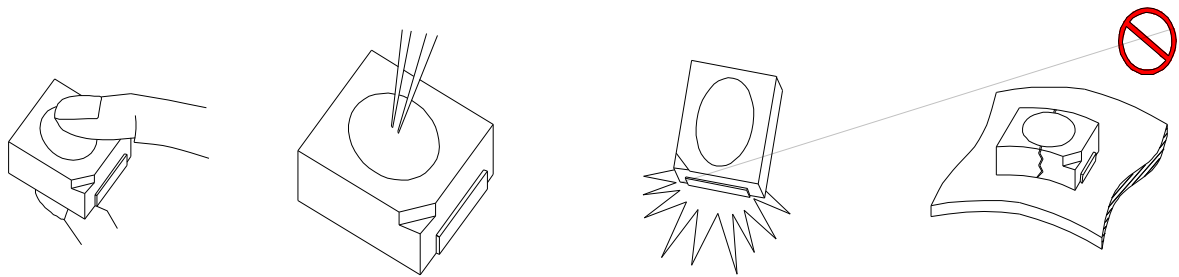


Fig 4-1 Title

(5) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the mean while, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

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(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design.LED

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the



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Declare

This specification is written both in English and in Chinese and the latter is formal.